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1A: SUBSTRATES: LTCC AND HTCC

HIGH FREQUENCY BANDWIDTH TRANSITION FOR HTCC HERMETIC PACKAGES..........1

Emad Elrifai

EGIDE, France

APPLICATION OF REACTIVE BONDING METHODS ON LTCC SUBSTRATES..........4

Erik Wiss[1], Alexander Schulz[2], Adam Yuile[1], Jens Müller[2], Steffen Wiese[1]

[1]Saarland University, Chair of Microintegration and Reliability, Germany; [2]TU Ilmenau, Electronics Technology Group, Germany

LTCC-BASED CERAMIC SUBSTRATES FOR IDENTIFICATION OF TRUSTWORTHY ELECTRONICS..........10

Uwe Krieger[1], Annett Schroeter[1], Franz Bechtold[1], Gunter Hagen[2], Adrian Goldberg[3]

[1]VIA electronic GmbH, Germany; [2]KMS Technology Center GmbH, Germany; [3]Fraunhofer Institute for Ceramic Technologies and Systems IKTS, Germany

1B: EMBEDDING

CONCEPTS FOR REALIZING HIGH-VOLTAGE POWER MODULES BY EMBEDDING OF SIC SEMICONDUCTORS..........13
Lars Böttcher, Andreas Ostmann, Thomas Löher, Manuel Seckel
Fraunhofer IZM, Germany

CERAMIC EMBEDDING OF SIC-SEMICONDUCTORS USING COFIRING TECHNOLOGY..........19
Steffen Ziesche[1], Jobin Varghese[1], Kathrin Reinhardt[1], Birgit Manhica[1], Andreas Schletz[2]
[1]Fraunhofer IKTS, Germany; [2]Fraunhofer IISB, Germany

CHARACTERIZATION OF EMBEDDED AND THINNED RF CHIPS..........24
Ran Yin[1,2], Helmuth P. E. Morath[1,3], Christian Hoyer[3], Krzysztof Nieweglowski[1,2], Karsten Meier[2], Karlheinz Bock[1,2]
[1]Centre for Tactile Internet with Human-in-the-Loop (CeTI), Germany;
[2]Institute of Electronic Packaging Technology, TU Dresden, Germany;
[3]Chair of Circuit Design and Network Theory, TU Dresden, Germany

2A: INTERCONNECT MATERIALS I

DEPOSITION OF FINE-PITCH INDIUM BUMPS ON SINGLE DIE..........30
Andreas Schneider[1], Navid Ghorbanian[1], David Burt[2], James Hollingham[1], Paul Booker[1], Toby G. Brookes[1], John D. Lipp[1],
Marcus J. French[1]

[1]STFC-RAL, United Kingdom; [2]Kelvin Nanotechnology Ltd., United Kingdom

SILVER BONDING WIRE – AN ALTERNATIVE FOR MECHANICAL SENSITIVE CHIP CONFIGURATIONS IN AUTOMOTIVE ELECTRONICS PACKAGING..........35
Robert Klengel[1], Sandy Klengel[1], Noritoshi Araki[2], Motoki Eto[2], Teruo Haibara[2], Takashi Yamada[2], Jochen Feldmann[3], Ralph Binner[3], Henk Peters[3], Achim Scheer[3], Vincent Chee[3]

[1]Fraunhofer IMWS, Germany; [2]Nippon Micrometal Corporation, Japan; [3]ELMOS Semiconductor SE, Germany

COPPER PUMPING ANALYSIS FOR CU/SIO2 HYBRID BONDING USING IN-SITU SPM IMAGING..........41
Ali Roshanghias[1], Jaroslaw Kaczynski[1], Ude Hangen[2]

[1]Silicon Austria Labs GmbH, Austria; [2]Bruker Nano GmbH, Germany

UNDERSTANDING THE CONTACT RESISTANCE IN AN ACF BONDING..........45
Helge Kristiansen[1], Knut Eilif Aasmundtveit[2], Giang Nghiem[2],
Molly Bazilchuk[3]

[1]Conpart AS, Norway; [2]University of South-Eastern Norway, Norway; [3]Ducky AS, Norway

2B: MEMS/SENSORS

MEMS MIRROR IN HERMETIC PACKAGE FOR ENHANCED PERFORMANCES..........50
Luca Maggi[1], Marco Del Sarto[1], Amedeo Maierna[1], Mark Shaw[1], Roberto Carminati[1], Gianluca Mendicino[1], Davide Rotta[2], Marco Chiesa[2], Aina Serrano[2], Antonella Bogoni[3]
[1]STMicroelectronics, Italy; [2]CamGraPhIC, Italy;
[3]Sant'Anna School of Adanced Studies, Italy

INNOVATIVE SILICON-CERAMIC (SICER) TECHNOLOGY FOR HIGH-STRENG-TH PRESSURE SENSOR APPLICATION USING DIFFERENT MANUFACTURING METHODS..........55
Cathleen Kleinholz[1], Michael Fischer[1], Nam Gutzeit[1], Andrea Cyriax[2], Michael Hintz[2], Thomas Ortlepp[2], Jens Müller[1]
[1]Technische Universität Ilmenau, Germany;
[2]CiS Forschungsinstitut für Mikrosensorik GmbH, Germany

FROM MEMS STRIP TO MEMS UNIT: A COMPREHENSIVE SIMULATION APPROACH TO WARPAGE..........61
Andrea Ratti[1], Daniele Simoncini[1], Annbel Adolfo[2], Marco Del Sarto[1], Patrick Fedeli[1], Alex Gritti[1], Luca Maggi[1], Teresa Napolitano[1], Mark Andrew Shaw[1], Jefferson Talledo[2]
[1]STMicroelectronics, Italy; [2]STMicroelectronics, Philippines

GAS PERMEABLE PROTECTION CAPS FOR WAFER LEVEL CHIP SCALE PACKAGING (WLCSP) OF MEMS ENVIRONMENTAL SENSORS..........67
Ole Behrmann, Thomas Lisec, Björn Gojdka
Fraunhofer ISIT, Germany

3A: SUBSTRATES – THICK FILM AND CU INTERCONNECTS

ADDITIVE METALLIZATION OF ALUMINA WITH COPPER-TITANIUM POWDER BLENDS FOR POWER ELECTRONIC APPLICATIONS..........71

Christoph Hecht[1],
Eric Schadow[1], Mario Sprenger[1], Felix Häußler[1], Thomas Stoll[2], Jörg Franke[1]

[1]IFriedrich-Alexander-Universtität Erlangen-Nürnberg, Nuremberg, Germany;
[2]TUM School of Engineering and Design, Munich, Germany

NEGATIVE-TONE PHOTO-DEFINABLE POLYIMIDE WITH HIGH THERMAL STABILITY AND THICK FILM PROCESSABILITY..........77

Hitoshi Araki, Takayuki Kaneki, Yu Shoji, Chika Hibino
Toray Industries Inc., Japan

3B: ADHESIVES AND ENCAPSULANTS

EPOXY MOLDING COMPOUND BLEEDING REDUCTION ON SURFACE MOUNT SEMICONDUCTOR DEVICE..........81
Federico Leone[1], Fulvio Viviani[1], Hidetoshi Seki[2], Masami Ishii[2]
[1]STMicroelectronics, Italy; [2]Sumitomo Bakelite Singapore Pte. Ltd, Singapore

INFLUENCE OF THERMALLY AGED UNDERFILL ON FLIP-CHIP PACKAGES..........85
Kevin Cox, Ghassan Abu-Hamdeh, Matt Borden
Tektronix Component Solutions, United States of America

ADHESIVE SOLUTIONS FOR CLOSED CAVITY PACKAGING..........91
Patrick Schirmer, Severin Ringelstetter
DELO Industrie Klebstoffe GmbH & Co. KGaA, Germany

4A: INTERCONNECT MATERIALS II

DEVELOPMENT OF A STRETCHABLE AND REMOVABLE ELECTRICAL INTERCONNECTION SOLUTION FOR ULTRA-THIN ELECTRONIC COMPONENTS..........94
Auriane Despax-Ferreres[1], Pascal Tiquet[1], Jean-Charles Souriau[2],
Vincent Jousseaume[2], Julia De Girolamo[1]
[1]Univ. Grenoble Alpes, CEA, Liten, Grenoble, France;
[2]Univ. Grenoble Alpes, CEA, Leti, Grenoble, France

UV LASER COPPER PAD SURFACE EXPOSURE FOR LASER DIRECT STRUCTURING (LDS) OF INTERCONNECTION..........100
Guendalina Catalano, Alessandro Mellina Gottardo, Riccardo Villa
ST microelectronics, Italy

FINE PITCH MICRO INDIUM BUMP INTERCONNECT FLIP CHIP BONDING..........106
Travis Scott
Finetech GmbH & Co.KG, Germany

4B: MEDICAL

INITIAL LIFE TEST OF SILICONE ENCAPSULATED FR4 PRINTED CIRCUIT BOARDS FOR PRE-CLINICAL ACTIVE IMPLANTS..........111
Ishpa Ali[1], Fei Xue[1], Carlos Perez Henriquez[1], Thomas Niederhoffer[1], Ahmad Shah Idil[1], Dai Jiang[2], Henry Thomas Lancashire[1]
[1]Department of Medical Physics and Biomedical Engineering, University College London, London, UK.; [2]Department of Electronic and Electrical Engineering, University College London, London, UK.

VOIDING IN PARYLENE-C ENCAPSULATION OF SURFACE MOUNT LEDS FOR AN OPTOGENETIC EPILEPSY NEUROPROSTHESIS..........115
Ahmad Shah Idil[1], Richard Bailey[2], Johannes Gausden[2], Antony O'Neill[2], Nick Donaldson[1]
[1]University College London, UK; [2]Newcastle University, UK

ASSEMBLY OF PRINTED INTERCONNECTS FOR IMMOBILIZED PROTEIN MICROFLUIDIC ASSAYS..........120
Qianwen Xu[1], Jeffery C. C. Lo[1], Yusong Guo[1], S. W. Ricky Lee[1,2,3]
[1]The Hong Kong University of Science and Technology, Hong Kong, PRC;
[2]HKUST Shenzhen-Hong Kong Collaborative Innovation Research Institute, PRC;
[3]HKUST LED-FPD Technology R&D Center at Foshan, PRC

FLEXIBLE HYBRID ELECTRONICS ON WEARABLE HEALTHCARE APPLICATION..........124
Ming-Hung Chen
ASE, Taiwan

POSTER SESSION

01 **TESTING OF ELECTROMIGRATION RESISTANCE OF COPPER AND SILVER THICK FILMS 129**
Jiri Hlina[1], Jan Reboun[1], Marek Simonovsky[2], Ales Hamacek[1]
[1]University of West Bohemia, Faculty of Electrical Engineering, Czech Republic; [2]Elceram a.s., Hradec Kralove, Czech Republic

02 **RELIABILITY TESTING OF RECYCLED SMD COMPONENTS REUSED IN E-TEXTILES AFTER AGEING BY WASHING CYCLES 134**
Martin Hirman, Jiří Navrátil, Andrea Benešová, František Steiner
University of West Bohemia, Czech Republic

03 **PROCESS WINDOW OF MINI-LED DISPLAY PANEL PACKAGING USING LASER ASSISTED BONDING TECHNOLOGY 139**
Yong Sung Eom, Gwang-Mun Choi, Ki-Seok Jang, Ji-Ho Joo, Chan-Mi Lee, Jin-Heuk Oh, Seok-Hwan Moon, Kwang-Seong Choi
ETRI, Republic of South Korea

04 **EFFECT OF SURFACE MICROSTRUCTURE ON JOINTS USING NANOPOROUS CU SHEET FOR POWER DEVICES 143**
Hiroshi Nishikawa[1], Byungho Park[2], Mikiko Saito[3], Jun Mizuno[3]
[1]Joining and Welding Research Institute, Osaka Universit, Japan; [2]Graduate School of Engineering, Osaka University, Japan; [3]Research Organization for Nano & Life Innovation, Waseda University, Japan

05 **INVESTIGATION OF ALUMINUM AND GOLD FLIP-CHIP BONDING FOR QUANTUM DEVICE INTEGRATION 147**
Imants Cirulis[1], Uwe Zschenderlein[2], Silvia Braun[1], Moritz Radestock[1], Remi Pantou[1], Klaus Vogel[1], Franz Selbmann[1], Steffen Kurth[1], Bernhard Wunderle[1,2], Harald Kuhn[1,2]
[1]Fraunhofer Institute for Electronic Nano Systems, Germany; [2]Technical University Chemnitz, Germany

06 **ADHESION COPPER/MOLDING COMPOUND: MODELING AND CHARACTERIZATION 152**
Marco Rovitto[1], Samuele Zalaffi[1], Carlo Passagrilli[1], Claudio Maria Villa[1], Luca Andena[2], Stefano Mariani[2]
[1]STMicroelectronics, Italy; [2]Polytechnic University of Milan, Italy

07 **A HIGH-DENSITY ORGANIC PACKAGE SOLUTION TO W-BAND SIGE FLIP-CHIP APPLICATIONS 158**
Fırat Altuntaş, Nihan Öznazlı, Olcay Kalkan, Emrah Koç
Aselsan A.Ş, Turkey

08 **THERMAL DESIGN OF STACKED POWER MODULES FOR ELECTRIC DRIVE APPLICATIONS..........162**
Jianfeng Li, Yuekang Du, Xingzhi Wang, Liangjie Liu, Yong Pang, Feixiang Liu
Zhuzhou CRRC Times Electric UK Innovation Centre, United Kingdom

09 **LAMINATION OF CAPACITIVE MICROMACHINED ULTRASONIC TRANSDUCER ON A PIEZOELECTRIC ARRAY: PROCESS AND EVALUATION..........168**
Duy Hoang Le, Tung Manh, Lars Hoff
University of South-Eastern Norway (USN), Norway

10 **ASSEMBLY OF ULTRA-THIN MEMS DEVICE ON DRIVER CHIP USING ANISOTROPIC CONDUCTIVE FILM 172**
Hoang-Vu Nguyen, Knut Eilif Aasmundtveit
University of South-Eastern Norway, Norway

11 **AN INNOVATIVE CONFORMAL ELECTRONICALLY SCANNED ARRAY ANTENNA FOR FULL 360° STEERABILITY IN THE KA-BAND 177**
Peter Uhlig, Aline Friedrich, Markus Krengel, Winfried Simon, Oliver Litschke
IMST GmbH, Germany

12 **THERMALLY CONDUCTIVE POLYMER COMPOSITES WITH HEXAGONAL BORON NITRIDE FOR MEDICAL DEVICE THERMAL MANAGEMENT..........181**
Nu Bich Duyen Do[1], Kristin Imenes[1], Knut E. Aasmundveit[1], Hoang-Vu Nguyen[1], Erik Andreassen[1,2]
[1]University of South-Eastern Norway, Norway; [2]SINTEF Industry, Norway

13 MICROSTRUCTURAL BASED RELIABILITY INVESTIGATION OF WATER-AND SUSPENSION FREE PREPARED INTEGRATED ELECTRONIC PACKAGES..........189
Sandy Klengel, Robert Klengel, Tino Stephan
Fraunhofer IMWS, Germany

14 NUMERICAL STUDY ON THE INFLUENCE OF POLYIMIDE THICKNESS AND CURING TEMPERATURE ON WAFER BOW IN WAFER LEVEL PACKAGING..........194
Prashant Kumar Singh[1,2], Patrick Rohlfs[1], Gunther Sandmann[1], Kashi Vishwanath Machani[1], Dirk Breuer[1], Karsten Meier[2], Frank Kuechenmeister[1], Marcel Wieland[1], Karlheinz Bock[2]
[1]GlobalFoundries Dresden Module One LLC & Co. KG, Germany; [2]Technische Universität Dresden, Institute of Electronic Packaging Technology, Germany

15 IMPROVEMENT OF BONDING STRENGTH AND THERMAL SHOCK RELIABILITY FOR AG SINTER JOINING DIRECT ON AL SUBSTRATE..........200
Chuantong Chen[1], Ran Liu[1], Koji Kobayashi[2], Hideyo Osanai[2], Zheng Zhang[1], Katsuaki Suganuma[1]
[1]Osaka University; [2]DOWA POWER DEVICE Co., Ltd

16 INTERCONNECT STRESS TESTING AS A TOOL FOR ASSESSMENT OF RELIABILITY OF MODERN PCB'S..........204
Marek Koscielski, Krzysztof Glinski, Dariusz Ostaszewski, Tomasz Klej, Jan Oklej, Aneta Cholaj, Wojciech Steplewski, Stefan Galinski
Łukasiewicz Research Network - Tele and Radio Research Institute, Poland

17 HIGH SPEED TRANSMISSION CHARACTERISTICS ON GLASS BASED INTERPOSERS..........209
Satoru Kuramochi, Masaya Tanaka, Takahiro Tai
Dai Nippon Printing, Japan

18 DESIGN, FABRICATION, AND CHARACTERIZATION OF A 4H-SIC CMOS READOUT CIRCUIT FOR MONOLITHIC INTEGRATION WITH SIC SENSORS..........215
Romina Sattari, Henk van Zeijl van Zeijl, Guoqi Zhang
Department of Microelectronics, Delft University of Technology, The Netherlands

5A: SINTERING I

RELIABILITY OF COPPER SINTERED INTERCONNECTS UNDER EXTREME THERMAL SHOCK CONDITIONS..........218

Sri Krishna Bhogaraju[1], Francesco Ugolini[2], Alessio Greci[2], Gordon Elger[1]

[1]Technische Hochschule Ingolstadt, Germany; [2]AMX Automatrix srl, Italy

RAPID SINTERING OF INKJET PRINTED CU COMPLEX INKS USING LASER UNDER AIR 223

Nihesh Mohan[1], Sri Krishna Bhogaraju[1], Juan Ignacio Ahuir-Torres[2], Hiren Kotadia[2,3], Gordon Elger[1]

[1]Institute of Innovative Mobility, Technische Hochschule Ingolstadt, Germany;
[2]School of Engineering, Liverpool John Moores University, UK;
[3]WMG, University of Warwick, UK

IMPROVING SEMICONDUCTOR RELIABILITY OF SILVER SINTER DIE ATTACH MATERIALS FOR LARGE DIE ON LEAD FRAME APPLICATIONS..........230

Ruud De Wit[1], Edsger Smits[2]

[1]Henkel Nederland BV, The Netherlands; [2]Chip Integration Technology Center (CITC), The Netherlands

5B: EQUIPMENT / INSPECTION

PICK AND PLACE OF SENSITIVE CHIPS WITH VACUUM-FREE GECOMER® TOOLS..........238

Lukas Lorenz[1], Thomas Ludewig[1], Kai Swiecinski[1], Henrik Ollmann[2], Amirabbas Razkordanisharahi[2], Volker Bock[1]

[1]Fraunhofer IPMS, Germany; [2]INNOCISE GmbH, Germany

RESEARCH OF CHIP PLACEMENT ACCURACY FOR FAN-OUT WLP USING A NOVEL SELF-ASSEMBLY STAGE..........244

Tadatomo Yamada, Ken Takano, Toshiaki Menjo, Shinya Takyu

LINTEC Corporation, Japan

ONE-PROBE NANOPROBING OF POWER DEVICES AND ELECTRONIC PACKAGES..........250

Chengliang Huang[1], Vignesh Viswanathan[1], Greg M. Johnson[2], Andreas Rummel[3], Heiko Stegmann[4], Elliott Andrew[5]

[1]Carl Zeiss Pte Ltd, Singapore; [2]Zeiss Microscopy, United States of America; [3]Kleindiek Nanotechnik, Germany; [4]Zeiss Microscopy, Germany; [5]Zeiss Microscopy, UK

6A: PHOTONICS AND OPTICS

STUDY OF SPATIAL DISTORTION IN INP NANOPHOTONIC MEMBRANES ON DIFFERENT CARRIER SUBSTRATES..........255

Salim Abdi[1], Aleksandr Zozulia[1], Jeroen Bolk[2], Erik Jan Geluk[2], Yuqing Jiao[1], Kevin Williams[1]

[1]Eindhoven Hendrik Casimir Institute (EHCI), Eindhoven University of Technology; [2]Nanolab@tu/e, Eindhoven University of Technology

LASER-ASSISTED BONDING APPROACH FOR PHOTONIC INTEGRATION PROCESSES..........260

Aleksandr Vlasov, Topi Uusitalo, Evgenii Lepukhov, Heikki Virtanen, Samu-Pekka Ojanen, Jukka Viheriälä, Mircea Guina

Tampere University, Finland

INTEGRATION OF MULTI-LITHOGRAPHY TECHNOLOGIES FOR THE FABRICATION OF FLEXIBLE OPTICAL LINK..........264

Akash Sunilkumar Mistry, Krzysztof Kamil Nieweglowski, Karlheinz Bock

Technical University of Dresden, Germany

HYBRID LITHOGRAPHY FABRICATION OF SINGLE MODE OPTICS FOR SIGNAL REDISTRIBUTION AND COUPLING..........269

David Weyers, Krzysztof Nieweglowski, Karlheinz Bock

Technological University Dresden, Germany

6B: SOLDER / SOLDERING

COMPARING THE SOLDERABILITY OF DIFFERENT SAC0307 COMPOSITE SOLDER PASTES..........277
Balázs Illés[1,2], Halim Choi[1], Agata Skwarek[2]
[1]Budapest University of Technology and Economics, Hungary;
[2]Łukasiewicz Research Network - IMiF, LTCC Technology and Printed Electronics Research Group, Poland

ANISOTROPIC SOLDER PASTE (ASP) MATERIAL SOLUTION FOR LASER ASSISTED BONDING (LAB) PROCESS..........282
Ki-Seok Jang, Yong-Sung Eom, Gwang-Mun Choi, Ji-Ho Joo, Jin-Hyuk Oh, Chan-Mi Lee, Yoon-Hwan Moon, Seok-Hwan Moon, Kwang-Seong Choi
Electronics and Telecommunication Research Institute, Republic of South Korea

DURABILITY OF LEAD-FREE SOLDER INTERCONNECTIONS FOR PRINTED CIRCUIT BOARD APPLICATIONS: COMPARING ENERGY-BASED THERMO-MECHANICAL FATIGUE MODELS..........286
Chien-Ming Huang, Jeffrey W. Herrmann
University of Maryland, United States of America

7A: SINTERING II

AN EXPERIMENTAL INVESTIGATION OF A FLEXIBLE SINTERED SILVER JOINT FOR MICRO-JOINING BASED ON A DESIGN OF EXPERIMENTS..........292
Laurent Vivet[1], Lahouari Benabou[2], Olivier Simon[2]
[1]VALEO, THS Material Laboratory, France;
[2]UVSQ, University of Paris-Saclay, France

UNDERSTANDING CU SINTERING AND ITS ROLE ON CORROSION BEHAVIOUR FOR HIGH-TEMPERATURE MICROELECTRONIC APPLICATION..........297
Juan Ignacio Ahuir-Torres[1], Sri Krishna Bhogaraju[2], Geoff West[3], Gordon Elger[2], Hiren Kotadia[1,3]
[1]Liverpool John Moores University, UK;
[2]Technische Hochschule Ingolstadt, Germany; [3]The University of Warwick, UK

INSPECTION TECHNIQUES USING SCANNING ACOUSTIC MICROSCOPY FOR SILVER SINTERING APPLICATIONS IN POWER ELECTRONIC MODULES..........302
Heaklig Ayala[1,2], Jose Ortiz-Gonzalez[1], Mohamed-Amer Karout[1], James Cotty[2], Tim Rumney[2], Philip Mawby[1]
[1]University of Warwick, United Kingdom; [2]Custom Interconnect Limited, United Kingdom

7B: HERMETIC/CONFORMAL COATINGS/TIMS

CHARACTERIZATION OF A NOVEL COST-EFFICIENT AND ENVIRONMENTALLY FRIENDLY GRAPHENE-ENHANCED THERMAL INTERFACE MATERIAL 309

Sihua Guo[1], Kristoffer Harr (Martinsen)[2], Amos Nkansah[2], Jiajia Chen[1], Zhiyang Shen[1], Murali Murugesan[2], Hongfeng Zhang[2], Lars Almhem[2], Arto Ahtonen[2], Jin Chen[3], Johan Liu[1,4,5]

[1]SMIT Center, Shanghai University, PRC; [2]SHT Smart High-Tech AB, Sweden; [3]Shanghai Ruixi New Materials High Tech Co. Ltd., PRC; [4]Electronics Materials and Systems Laboratory, Chalmers University of Technology, Sweden; [5]School of Energy and Materials Science, Shanghai Poly-Tech University, PRC

EVOLUTION OF GETTER TECHNOLOGY IN ELECTRONIC HERMETIC PACKAGING 313

Luca Mauri, Giovanni Zafarana, Enea Rizzi, Alessio Corazza

SAES Getters, Italy

ADVANCES IN PARYLENE ADHESIVE BONDING FOR THE REALIZATION OF BIOCOMPATIBLE MICROSYSTEMS..........319

Franz Selbmann[1,2], Frank Roscher[1], Maik Wiemer[1], Harald Kuhn[1,3], Yvonne Joseph[2]

[1]Fraunhofer Institute for Electronic Nano Systems ENAS, Germany; [2]TU Bergakademie Freiberg, Institute for Electronic and Sensor Materials, Germany; [3]TU Chemnitz, Center for Microtechnologies, Germany

8A: FLIP CHIP

FLIP-CHIP INTERCONNECTS BASED ON SINGLE METAL-COATED POLYMER SPHERES..........325
Van Long Huynh, Knut Eilif Aasmundtveit, Hoang-Vu Nguyen
University of South-Eastern Norway, Norway

20µM COPPER MICRO-BUMP BONDING THROUGH A SILVER METALLIZATION FOR ADVANCED PACKAGING UNDER A LOW-PRESSURE CONDITION..........330
Zheng Zhang[1], M.-C. Hsieh[1], A. Suetake[1], H. Yoshida[1], R. Okumuara[1], N. Kagami[1], Kazamasa Okamoto[1], Chuantong Chen[1], Kei Hashizume[2], N. Hasegawa[2], R. Yoshida[2], H. Homma[2], K. Suganuma[1]
[1]SANKEN, Osaka University, Japan; [2]Okuno Chemical Industries Co. Ltd,

PRACTICAL RESULTS TO DEMONSTRATE AN INCREASE IN THE RELIABILITY OF FLIP CHIP CONNECTIONS BY ADDING NANOPARTICLES TO SOLDER..........333
David Harvey[1], Teresa Manzanera[2], Kangkana Baishya[3], Guangming Zhang[1], Mohd Arif Anuar[4], Y. C. Chan[1], Nduka Ekere[1], Derek Braden[5]
[1]Liverpool John Moores University, Liverpool, UK; [2]University of Liverpool, Liverpool, UK; [3]Assam Engineering College, Guwahati, India; [4]UniMAP, Perlis, Malaysia; [5]Aptiv, Coventry, UK

DEVELOPMENT AND CHARACTERIZATIONS OF FINE PITCH FLIP-CHIP INTERCONNECTION USING SILVER SINTERING..........337
Julie Gougeon[1,2], Céline Feautrier[1], Laurent Mendizabal[1], Jean-Charles Souriau[1], Mona Tréguer-Delapierre[2]
[1]CEA Leti, France; [2]ICMCB, France

8B: RELIABILITY AND SUSTAINABILITY

ANALYSIS OF THE IMPACT OF ENVIRONMENTAL CONDITIONS ON THE RELIABILITY IN 5G PCB ASSEMBLIES..........341
Hans Walter[1], Marius van Dijk[1], Julia-Marie Köszegi[1], Saskia Huber[1], Olaf Wittler[1], Michael Kaiser[1], Martin Schneider-Ramelow[1,2]
[1]Fraunhofer IZM, Germany; [2]Technische Universität Berlin, Germany

EVALUATION OF THE ENVIRONMENTAL IMPACT WITHIN SEMICONDUCTOR PACKAGING MATERIALS..........348
Andrew Bainbridge, Lewis Clark, Kathleen Grant, Jeff Kettle
University of Glasgow, United Kingdom

MEASUREMENT AND SIMULATION OF MECHANICAL STRENGTH OF BACK-END-OF-LINE LAYER IN ADVANCED CMOS DIES..........352
Bart Vandevelde[1], Kevin Cox[2], Reza Moloudi[1], Riet Labie[1], Jason Krantz[2], Matt Borden[2], Kris Vanstreels[1], Mario Gonzalez[1]
[1]imec, Belgium; [2]Tektronix, United States of America

9A: MACHINE LEARNING

APPLICATION OF MACHINE LEARNING METHODS FOR PROCESS OPTIMIZATION IN ELECTRONIC PACKAGING PROCESSES..........357

Corinna Niegisch[1], Sabine Haag[1], Tanja Braun[2], Ole Hölck[2], Martin Schneider-Ramelow[3]

[1]Robert Bosch GmbH, Germany; [2]Fraunhofer IZM Berlin, Germany; [3]Technical University Berlin, Germany

PARTIAL DISCHARGE CHARACTERIZATION OF CERAMIC POWER ELECTRONICS CIRCUIT CARRIERS ASSISTED BY MACHINE LEARNING..........363

Johannes Drechsel, Lars Rebenklau, Henry Barth

Fraunhofer IKTS, Germany

9B: SOLAR / SENSORS

IMPACT OF PAD LAYOUTS AND SOLDER VOLUME ON SELF-ALIGNMENT OF MICRO SOLAR CELLS..........373
Elisa Kaiser[1], Maike Wiesenfarth[1], Victor Vareilles[2], Henning Helmers[1]
[1]Fraunhofer ISE, Germany; [2]Université Grenoble Alpes, CEA LITEN, France

NOVEL LOW TEMPERATURE AND LOW PRESSURE SINTERING OF ADAS RADAR SENSOR ANTENNA STACK..........378
Sri Krishna Bhogaraju[1], Dirk Busse[2], Alexander Dahlbüdding[2], Philipp Hadrava[3], Hüseyin Erdogan[3], Gordon Elger[1]
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10A: HIGH FREQUENCY

CHARACTERIZATIONS FOR EWLB (EMBEDDED WAFER LEVEL BALL GRID ARRAY) ANTENNA IN MOLDED PACKAGE INTEGRATIONS IN 77GHZ AUTOMOTIVE APPLICATIONS..........384
M.-C. Hsieh[1], F. Zhang[2], F. Zhu[2], K. Liu[2], L. Chua[3], Y. Lin[3], J. Damalerio[3], Hin Hwa Goh[3], Kai Chong Chan[3], Zihao Chen[4]
[1]JCET Group Co. Ltd., Singapore; [2]Andar Technologies Co., Ltd.; [3]JCET Group Co. Ltd.,, Singapore; [4]Harbin Institute of Technology, Shenzhen, PRC

A DUAL-BAND DUAL-POLARIZED 2X2 ANTENNA ARRAY WITH BEAMFORMING FOR 5G AIP AND MMWAVE APPLICATIONS..........389
Sheng-Chi Hsieh, Wen-Chun Hsiao, Hong-Sheng Hong-Sheng, Cheng-Yu Ho, Chen-Chao Wang
ASE group /Advanced Semiconductor Engineering, Taiwan

ANALYSIS AND CHARACTERIZATION OF CASTELLATED HOLES AS RF INTERCONNECTS FOR MODULAR MILLIMETER-WAVE DEVICES..........394
Paul Perlwitz[1,2], Christian Tschoban[1], Ivan Ndip[1], Harald Pötter[1], Martin Schneider-Ramelow[1,2]
[1]TU Berlin; [2]Fraunhofer IZM, Germany

HIGH-Q KU-BAND MICROSTRIP SPIRAL RESONATOR IN FAN-OUT WAFER-LEVEL PACKAGING TECHNOLOGY FOR VCO APPLICATIONS..........401
M. Chernobryvko[1], M. P. Kaiser[1], K. S. Murugesan[1], D. Kuylenstierna[2], J.-M. Köszegi[1], R. Gernhardt[1], T. Braun[1], I. Ndip[1], M. Schneider-Ramelow[1]
[1]Fraunhofer IZM Berlin, Germany; [2]Chalmers University of Technology, Sweden

10B: POWER MODULES

THERMAL-MECHANICAL ANALYSIS OF A POWER MODULE WITH PARAMETRIC MODEL ORDER REDUCTION..........405
Sheikh Rokibul Hassan[1], Pushparajah Rajaguru[1], Stoyan Stoyanov[1], Christopher Bailey[2]
[1]University of Greenwich, United Kingdom; [2]School of Electrical, Computer and Energy Engineering, Arizona State University, USA

THICKNESS EFFECT OF COPPER CLIPS ON POWER MODULE PACKAGING DESIGN..........411
H. Wan[1], N. Iosifidis[1], X. Zhang[1], R. Rong[2], M. Antoniou[1], P. Mawby[1]
[1]University of Warwick, United Kingdom; [2]MacMic Science & Technology Co., Ltd, China

HIGH FREQUENCY THIN FILM MAGNETICS-ON-SILICON WITH IMPROVED INDUCTANCE AND RESISTANCE..........416
Martin Sittner
Würth Elektronik eiSos Group, Germany

ENHANCED RELIABILITY FOR POWER MODULES VIA A NEW AG/SI SINTER JOINING STRATEGY..........421
Y. Liu[1], C. Chen[1], Koji S. Nakayama[1], Minoru Ueshima[2], Takeshi Sakamoto[2], Takuya Naoe[3], Hiroshi Nishikawa[3], Katsuaki Suganuma1
[1]Flexible 3D System Integration Laboratory, Osaka University, Japan; [2]Daicel Corporation, Japan; [3]Joining and Welding Research Institute, Osaka University, Japan